



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**Notification# 20241217005.0
Datasheet for LM6172
Information Only Datasheet**

Date: December 18, 2024
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the Change Management team.

Sincerely,

Change Management Team
SC Business Services

20241217005.0
Information Only Datasheet
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
LM6172IN/NOPB	LM6172IN/NOPB

Technical details of this Product Change follow on the next page(s).

PCN Number:	20241217005.0		PCN Date:	December 18, 2024																																		
Title:	Datasheet for LM6172																																					
Customer Contact:	Change Management team	Dept:	Quality Services																																			
Change Type:	Electrical Specification																																					
PCN Details																																						
Description of Change:																																						
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  LM6172 SNOS792E – MAY 1999 – REVISED DECEMBER 2024 <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="text-align: left;">Changes from Revision D (March 2013) to Revision E (December 2024)</th> <th style="text-align: right;">Page</th> </tr> </thead> <tbody> <tr> <td>• Updated the numbering format for tables, figures, and cross-references throughout the document.....</td> <td style="text-align: right;">1</td> </tr> <tr> <td>• Added <i>Package Information</i> table and <i>Pin Configuration and Functions, Specifications, ESD Ratings, Recommended Operating Conditions, Thermal Information, Detailed Description, Overview, Functional Block Diagram, Feature Description, Device Functional Modes, Application and Implementation, Typical Applications, Power Supply Recommendations, Layout, Layout Guidelines, Layout Example, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....</td> <td style="text-align: right;">1</td> </tr> <tr> <td>• Changed pin names and updated pinout diagram to reflect new naming convention.....</td> <td style="text-align: right;">3</td> </tr> <tr> <td>• Updated <i>Thermal Information</i> for the D (SOIC-8) and P (PDIP-8) packages.....</td> <td style="text-align: right;">4</td> </tr> <tr> <td>• Moved <i>DC and AC Electrical Characteristics</i> into one table for both $\pm 15V$ and $\pm 5V$ specifications.....</td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Changed output short-circuit current for D package.....</td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Updated unity-gain bandwidth from 100MHz to 80MHz for D package.....</td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Updated second harmonic distortion for D package.....</td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Updated third harmonic distortion for D package.....</td> <td style="text-align: right;">5</td> </tr> <tr> <td>• Changed output short-circuit current for D package.....</td> <td style="text-align: right;">7</td> </tr> <tr> <td>• Updated –3dB frequency for D package.....</td> <td style="text-align: right;">7</td> </tr> <tr> <td>• Updated phase margin for D package.....</td> <td style="text-align: right;">7</td> </tr> <tr> <td>• Updated second harmonic distortion for D package.....</td> <td style="text-align: right;">7</td> </tr> <tr> <td>• Updated third harmonic distortion for D package.....</td> <td style="text-align: right;">7</td> </tr> <tr> <td>• Deleted <i>Maximum Power Dissipation vs Ambient Temperature</i></td> <td style="text-align: right;">16</td> </tr> <tr> <td>• Changed thermal values in <i>Power Dissipation</i> to match <i>Thermal Information</i> table.....</td> <td style="text-align: right;">27</td> </tr> </tbody> </table>					Changes from Revision D (March 2013) to Revision E (December 2024)	Page	• Updated the numbering format for tables, figures, and cross-references throughout the document.....	1	• Added <i>Package Information</i> table and <i>Pin Configuration and Functions, Specifications, ESD Ratings, Recommended Operating Conditions, Thermal Information, Detailed Description, Overview, Functional Block Diagram, Feature Description, Device Functional Modes, Application and Implementation, Typical Applications, Power Supply Recommendations, Layout, Layout Guidelines, Layout Example, Device and Documentation Support, and Mechanical, Packaging, and Orderable Information</i> sections.....	1	• Changed pin names and updated pinout diagram to reflect new naming convention.....	3	• Updated <i>Thermal Information</i> for the D (SOIC-8) and P (PDIP-8) packages.....	4	• Moved <i>DC and AC Electrical Characteristics</i> into one table for both $\pm 15V$ and $\pm 5V$ specifications.....	5	• Changed output short-circuit current for D package.....	5	• Updated unity-gain bandwidth from 100MHz to 80MHz for D package.....	5	• Updated second harmonic distortion for D package.....	5	• Updated third harmonic distortion for D package.....	5	• Changed output short-circuit current for D package.....	7	• Updated –3dB frequency for D package.....	7	• Updated phase margin for D package.....	7	• Updated second harmonic distortion for D package.....	7	• Updated third harmonic distortion for D package.....	7	• Deleted <i>Maximum Power Dissipation vs Ambient Temperature</i>	16	• Changed thermal values in <i>Power Dissipation</i> to match <i>Thermal Information</i> table.....	27
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These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/LM6172																																						
Reason for Change:																																						
To accurately reflect device characteristics.																																						
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																																						
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Changes to product identification resulting from this PCN:																																						
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